

PCB Assembly Technical Specifications

ITEM	TECHNICAL PARAMETERS	
Assembly Services	<ul style="list-style-type: none">➤ SMD & Through-Hole Assembly.➤ Electronic Device Assembly.➤ In-Circuit Testing.➤ Automatic Pick & Place.➤ Automatic Wave Soldering. Automatic Stencil Printing.➤ Automatic Reflow Soldering.➤ Automatic Adhesives Dispensing.➤ Automatic Adhesives Curing.➤ Automatic Ultrasonic Vapor Degreasing.	
Min. SM Pitch	0.4mm	0.015"
Max Board Size	370mm x 470mm	14.57" x 18.50"
Layers	1-20 layers	1-20 layers
Component Sizes	Down to 0402	
Lead Time	3 - 5 working days	
Quality Standards	ISO9001-2000, ANS/IPC-A-610B	